Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-6 (cancelled)

7 (original). An interconnection structure comprising:

a dielectric layer;

a first metallization pattern on the dielectric layer, the first metallization pattern including at least one etch stop having a perimeter defining at least one etch stop opening;

a cured adhesive on a portion of the dielectric layer, the adhesive not present in an area aligned with the at least one etch stop;

at least one electrical device being attached to the dielectric layer by the adhesive such that an active area of the at least one electrical device is aligned with the etch stop perimeter.

8 (currently amended). ~~A probe comprising:~~ The interconnection structure of claim 16 wherein the interconnection structure comprises a probe and further includes

~~at least one energy-oriented probe electrical device including an active area and at least two device pads;~~

~~a dielectric layer having an opening aligned with the active area of the electrical device;~~

~~an adhesive coupling the dielectric layer and a non-active area of the device;~~

at least two vias extending through the dielectric layer to ~~the~~ at least two device pads of the at least one electrical device; and

a metallization pattern extending into the at least two vias to contact the at least two device pads to couple the electrical device pads to probe equipment.

9-15 (canceled).

16 (currently amended). An interconnection structure comprising:

a dielectric layer;

a first portion of cured adhesive;

a second portion of cured adhesive;

at least one electrical device being attached to the dielectric layer by the second portion of cured adhesive such that an active area of ~~the~~ at least one electrical device is aligned with the at least one predetermined area defined by the first portion of cured adhesive, the first portion of the cured adhesive being adhesively attached to the dielectric layer and not adhesively attached to the at least one electrical device.

17 (original). The interconnection structure of claim 16 further including a metallization pattern on the dielectric layer, the metallization pattern including at least one etch stop having a perimeter defining at least one etch stop opening aligned with the first portion of cured adhesive.